

NQS24LF BOM-style material declaration. BI Technologies Corporation

9/22/2010

No content here is banned per E.U. R.o.H.S.. Average mass of NQS24LF thin film network is 0.1 grams each. Prepared by Eric Arnold (714) 447-2565
Weights in table above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification		
Die	substrate	7.3%	Al2O3	1344-28-1	0.009			
			CaO	1305-78-8	2.25E-06			
			FeO2	1345-25-1	4.49E-06			
			MgO	1309-48-4	2.25E-06			
			MnO2	1313-13-9	8.99E-06			
			SiO2, amorphous	7631-86-9	1.35E-05			
			TiO2	13463-67-7	4.49E-06			
			nichrome resistor	0.00013%	NiCrOx	combination of 7440-02-0, 7440-47-3, & 1308-38-9	1.61E-07	
			nickel barrier	0.0002%	Ni	7440-02-0	2.30E-07	
			gold conductor	0.004%	Au	7440-57-5	5.44E-06	
BCB passivation	0.004%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	5.16E-06				
Leadframe	copper alloy	33.8%	Cu	7440-50-8	0.041			
			Fe	7439-89-6	9.79E-04			
			P	7723-14-0	1.25E-05			
			Zn	7440-66-6	5.00E-05			
			Sn	7440-31-5	0.002			
			Ag	7440-22-4	0.001			
Die adhesive	conductive epoxy	0.9%	Ag	7440-22-4	8.40E-04			
			trade secret	unknown	2.10E-04	non-hazardous		
Wire bonds	gold	0.04%	Au	7440-57-5	5.01E-05			
Molding compound	filled epoxy	55.7%	carbon black	1333-86-4	3.43E-04			
			epoxy resin, cresol novolac	29690-82-2	1.37E-03			
			SiO2, fused silica	60676-86-0	0.060			
			trade secret	unknown	0.007	non-hazardous		
			trade secret	unknown	4.95E-05	non-hazardous		
Ink marking	epoxy	0.04%	trade secret	unknown	4.95E-05	non-hazardous		